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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.
10/516,713	12/01/2004	Wolfgang Schnitt	DE02 0137 US	6751
65913 NXP, B.V.	7590 03/19/2007 EXAMINI			INER
NXP INTELLE	ECTUAL PROPERTY	LIU, BENJAMIN T		
M/S41-SJ 1109 MCKAY	DRIVE	ART UNIT	PAPER NUMBER	
SAN JOSE, CA	95131		2826	
SHORTENED STATUTOR	Y PERIOD OF RESPONSE	MAIL DATE	DELIVERY MODE	
3 MONTHS		03/19/2007	PAPER	

Please find below and/or attached an Office communication concerning this application or proceeding.

If NO period for reply is specified above, the maximum statutory period will apply and will expire 6 MONTHS from the mailing date of this communication.

	Application No.	Applicant(s)			
	10/516,713	SCHNITT ET AL.			
Office Action Summary	Examiner	Art Unit			
	Benjamin T. Liu	2826			
The MAILING DATE of this communication ap Period for Reply	pears on the cover sheet with the	correspondence address			
A SHORTENED STATUTORY PERIOD FOR REPL WHICHEVER IS LONGER, FROM THE MAILING D. - Extensions of time may be available under the provisions of 37 CFR 1. after SIX (6) MONTHS from the mailing date of this communication. - If NO period for reply is specified above, the maximum statutory period - Failure to reply within the set or extended period for reply will, by statut Any reply received by the Office later than three months after the mailin earned patent term adjustment. See 37 CFR 1.704(b).	OATE OF THIS COMMUNICATIO 136(a). In no event, however, may a reply be ti will apply and will expire SIX (6) MONTHS from e, cause the application to become ABANDONI	N. mely filed n the mailing date of this communication. ED (35 U.S.C. § 133).			
Status					
1) Responsive to communication(s) filed on 29 L	December 2006.				
·—	,				
· ·	Since this application is in condition for allowance except for formal matters, prosecution as to the merits is				
closed in accordance with the practice under	Ex parte Quayle, 1935 C.D. 11, 4	53 O.G. 213.			
Disposition of Claims					
4) ⊠ Claim(s) 1-10 is/are pending in the application 4a) Of the above claim(s) is/are withdra 5) □ Claim(s) is/are allowed. 6) ⊠ Claim(s) 1-10 is/are rejected. 7) □ Claim(s) is/are objected to. 8) □ Claim(s) are subject to restriction and/o	awn from consideration.	Minhloan Tran Primary Examiner			
Application Papers		Art Unit 2826			
9) The specification is objected to by the Examina 10) The drawing(s) filed on is/are: a) accomposed and applicant may not request that any objection to the Replacement drawing sheet(s) including the correct of the oath or declaration is objected to by the Examination.	cepted or b) objected to by the drawing(s) be held in abeyance. So ction is required if the drawing(s) is o	ee 37 CFR 1.85(a). bjected to. See 37 CFR 1.121(d).			
Priority under 35 U.S.C. § 119					
a) Acknowledgment is made of a claim for foreign a) All b) Some *-c) None of: 1. Certified copies of the priority document 2. Certified copies of the priority document 3. Copies of the certified copies of the priority application from the International Bureat * See the attached detailed Office action for a list	nts have been received. Its have been received in Applica Drity documents have been received (PCT Rule 17.2(a)).	tion No ved in this National Stage			
Attachment(s) 1) Notice of References Cited (PTO-892)	4)				
Notice of Draftsperson's Patent Drawing Review (PTO-948) Information Disclosure Statement(s) (PTO/SB/08) Paper No(s)/Mail Date	5) Notice of Informal 6) Other:				

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DETAILED ACTION

Response to Arguments

1. Applicant's arguments with respect to claims 1-10 have been considered but are most in view of the new ground(s) of rejection.

Claim Rejections - 35 USC § 102(b)

2. The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-10 are rejected under 35 U.S.C 102(b) as being anticipated by Zhang (5,886,364).

With regard to claim 1, figures 3A-3D of Zhang discloses a semiconductor-on-insulator (SOI) device, comprising: at least one isolating layer 31 made of a dielectric material (glass); at least one silicon substrate 34 arranged on the isolating layer 31; at least one component (40, 41, 42) integrated planarly in the silicon substrate 34, which component (40, 41, 42) has at least one slightly doped zone 41 laterally situated between a first highly doped zone 40 and a second highly doped zone 42; as well as at least a first planar metallization region (32, aluminum) arranged between the isolating layer 31 and the component (40, 41, 42), between the isolating layer 31 and the slightly doped zone 41 of the component (40, 41, 42), characterized in that at least a second planar, metallization region (38, aluminum) is arranged on the side of the silicon

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substrate 34 facing away from the isolating layer 31, in the area of the component (40, 41, 42) in the area of the slightly doped zone 41 of the component (40, 41, 42).

With regard to claim 2, figures 3A-3D of Zhang discloses the limitation, characterized in that a silicon substrate 34 comprising the component is fixed onto the isolating layer 31 with at least one fixing medium 33, with an adhesive layer 33.

With regard to claim 3, figures 3A-3D of Zhang discloses the limitation, characterized in that the first highly doped zone 40, the slightly doped zone 41 and the second highly doped zone 42 form at least one bipolar pnp transistor in the component (40, 41, 42); and the slightly doped zone 41 of the component (40, 41, 42) forms the n-doped region 41 of the pnp transistor (40, 41, 42).

With regard to claim 4, figures 3A-3D of Zhang discloses the limitation, characterized in that the first metallization region 32 is embedded in at least a first oxide-based passivation layer 33.

With regard to claim 5, figures 3A-3D of Zhang discloses the limitation, characterized in that on the side of the component (40, 41, 42) facing the isolating layer 31, at least one oxide layer (37, silicon oxide) borders on at least the component (40, 41, 42) or on the first passivation layer 33.

With regard to claim 6, figures 3A-3D of Zhang discloses the limitation, characterized in that between the component (40, 41, 42) and the second metallization region 38 at least a second buried oxide-based passivation layer 46 is arranged.

With regard to claim 7, figures 3A-3D of Zhang discloses the limitation, at least one isolating layer 31 made of a dielectric material (glass) is provided with at least one

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silicon substrate 34 using adhesive means; at least one component (40, 41, 42), having at least one slightly doped zone 41 laterally situated between a fast highly doped zone 40 and a second highly doped zone 42, is planarly integrated in the silicon substrate 34; and at least a first planar metallization region 32 is arranged between the isolating layer 31 and the slightly doped zone 41 of the component (40, 41, 42), characterized in that at least a second planar metallization region 38 is provided on the side of the silicon substrate 34 facing away from the isolating layer 31, in the area of the slightly doped zone 41 of the component (40, 41, 42).

With regard to claim 8, figures 3A-3D of Zhang discloses the limitation, characterized in that the first metallization region 32 is embedded in at least a first oxide-based passivation layer 33.

With regard to claim 9, figures 3A-3D of Zhang discloses the limitation, characterized in that at least a second buried oxide-based passivation layer 46 is arranged between the component (40, 41, 42) and the second metallization region 38.

With regard to claim 10, figures 3A-3D of Zhang discloses the application of at least a first planar metallization region 32 as well as at least a second planar metallization region 38 to electrically shield, on both sides, the at least one component (40, 41, 42) incorporated in the silicon substrate 34 of a SOI device, to electrically shield, on both sides, the at least one slightly doped zone 41 of the component (40, 41, 42). (Note abstract of Zhang)

Conclusion

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3. Applicant's amendment necessitated the new ground(s) of rejection presented in this Office action. Accordingly, **THIS ACTION IS MADE FINAL**. See MPEP § 706.07(a). Applicant is reminded of the extension of time policy as set forth in 37 CFR 1.136(a).

A shortened statutory period for reply to this final action is set to expire THREE MONTHS from the mailing date of this action. In the event a first reply is filed within TWO MONTHS of the mailing date of this final action and the advisory action is not mailed until after the end of the THREE-MONTH shortened statutory period, then the shortened statutory period will expire on the date the advisory action is mailed, and any extension fee pursuant to 37 CFR 1.136(a) will be calculated from the mailing date of the advisory action. In no event, however, will the statutory period for reply expire later than SIX MONTHS from the date of this final action.

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Benjamin T. Liu whose telephone number is (571) 272-6009. The examiner can normally be reached on Mon-Fri 9:30 AM-6:00PM.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Sue A. Purvis can be reached on 571 272 1236. The fax phone number for the organization where this application or proceeding is assigned is 571-273-8300.

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Information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see http://pair-direct.uspto.gov. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free). If you would like assistance from a USPTO Customer Service Representative or access to the automated information system, call 800-786-9199 (IN USA OR CANADA) or 571-272-1000.

BTL 3/8/2007